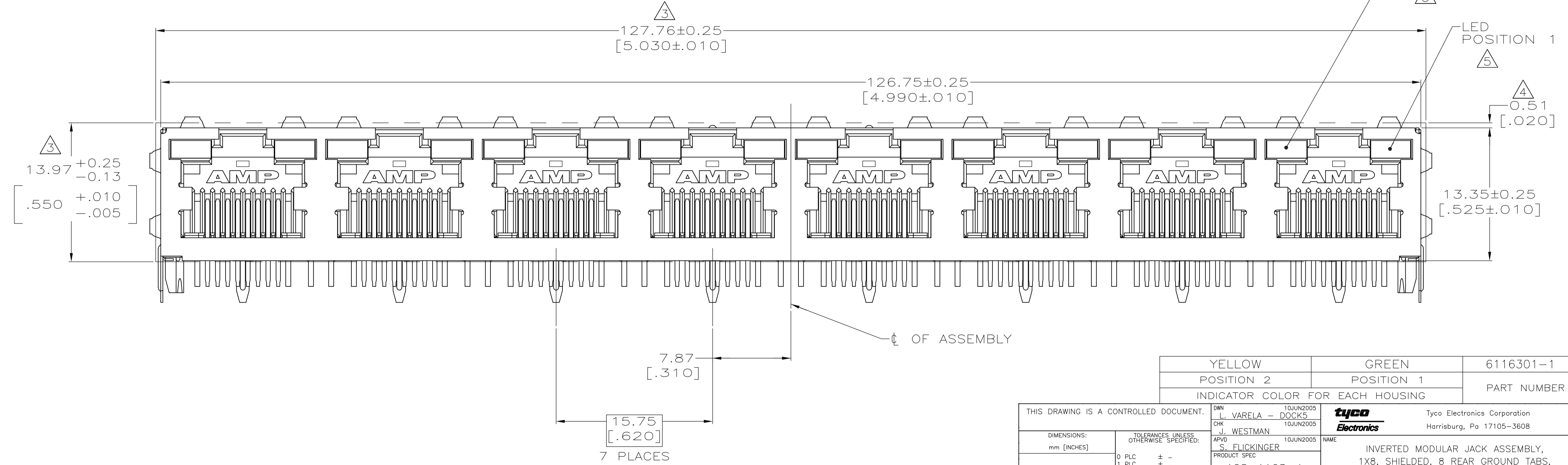
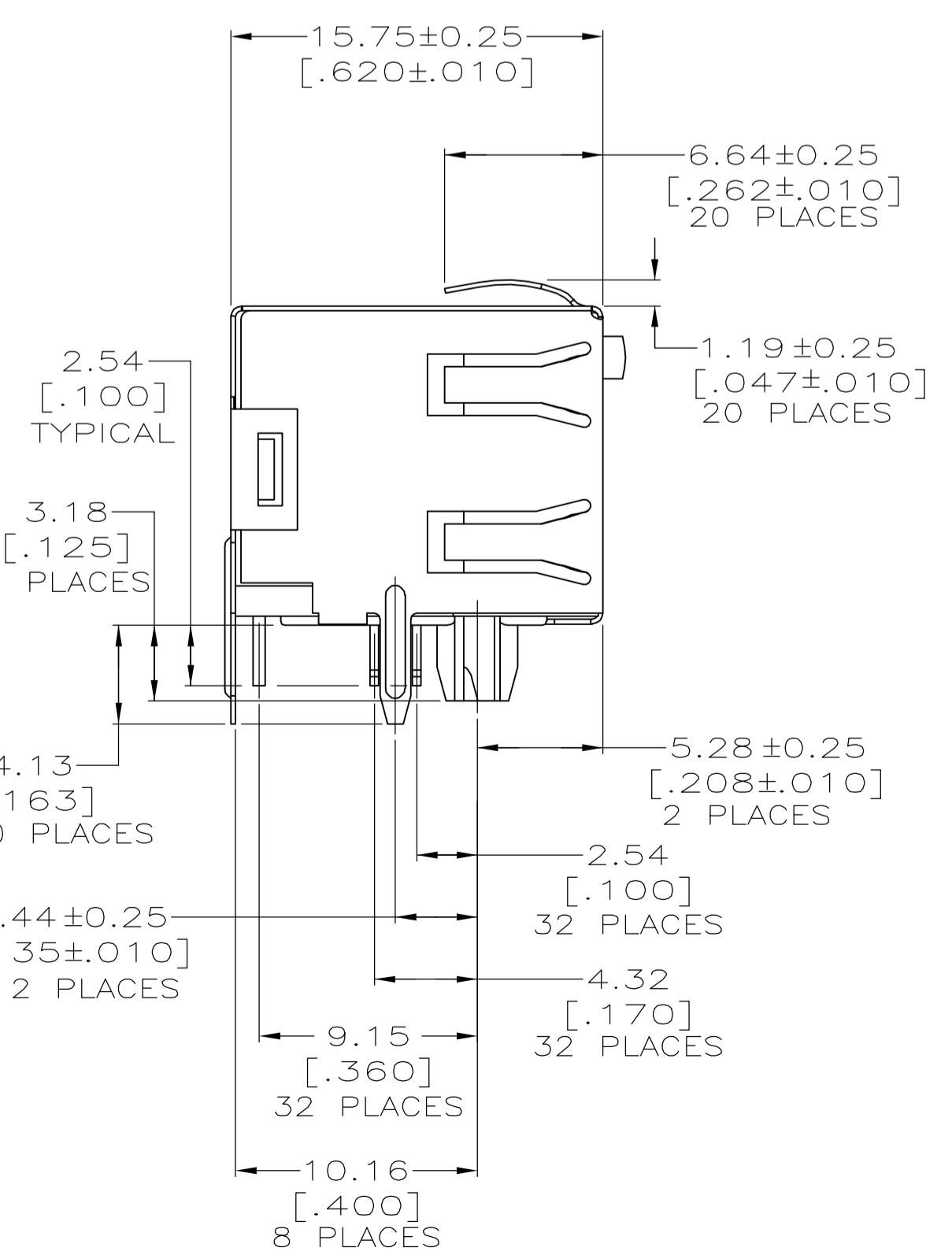
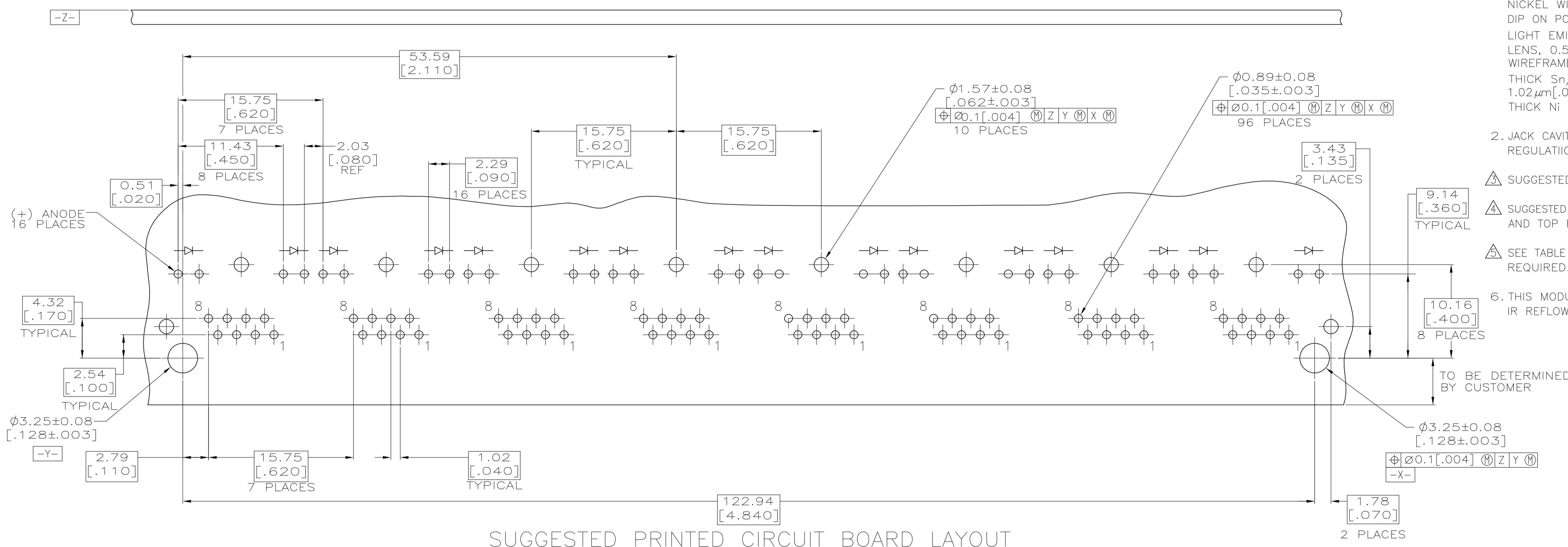


LOC		DIST		REVISIONS			
AA	22	F	LTR	DESCRIPTION	DATE	DWN	APVD
		A	REV PER EC	0511-0201-04	10JUN2005	LV	SF

MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE

- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



YELLOW	GREEN	6116301-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		
THIS DRAWING IS A CONTROLLED DOCUMENT.		
DIMENSIONS: mm (INCHES) TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.25(.01) 3 PLC ± 0.13(.005) 4 PLC ± - ANGLES ± -		DWN: L. VARELA - DOCKS CHK: J. WESTMAN APVD: S. FLICKINGER PRODUCT SPEC: 108-1163-4 APPLICATION SPEC: 114-2154 WEIGHT: - CUSTOMER DRAWING:
Tyco Electronics Corporation Harrisburg, Pa 17105-3608		NAME: INVERTED MODULAR JACK ASSEMBLY, 1X8, SHIELDED, 8 REAR GROUND TABS, PANEL GROUND, LED SIZE: A1 CAGE CODE: 00779 DRAWING NO: 6116301 RESTRICTED TO: - SCALE: 1:1 SHEET: 1 of 1 REV: A